

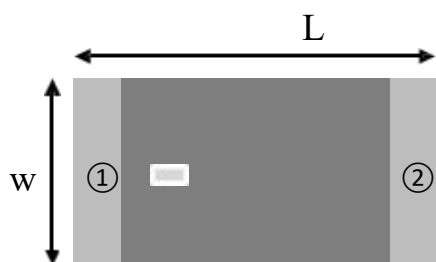
Features

1. Surface Mounted Devices with a small dimension of $2.0 \times 1.25 \times 0.6 \text{ mm}^3$ meet future miniaturization trend.
2. Embedded and LTCC (Low Temperature Co-fired Ceramic) technology is able to future integrate with system design as well as beautifying the housing of final product.
3. High Stability in Temperature / Humidity Change

Applications

1. Bluetooth
2. Wireless LAN
3. ISMband 2.4GHz wireless applications

Dimensions (Unit: mm)



(Top View)

①	INPUT
②	GND



(Bottom View)



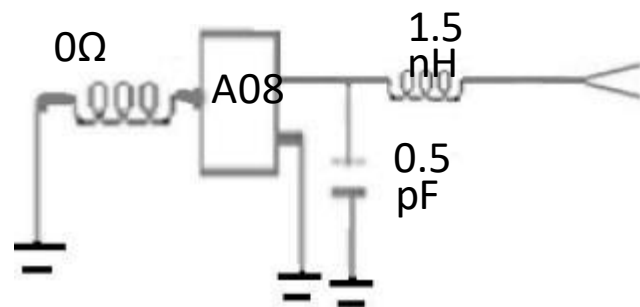
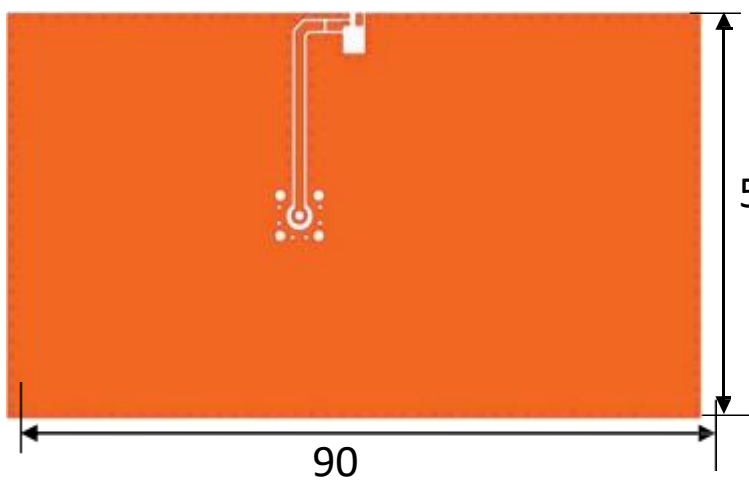
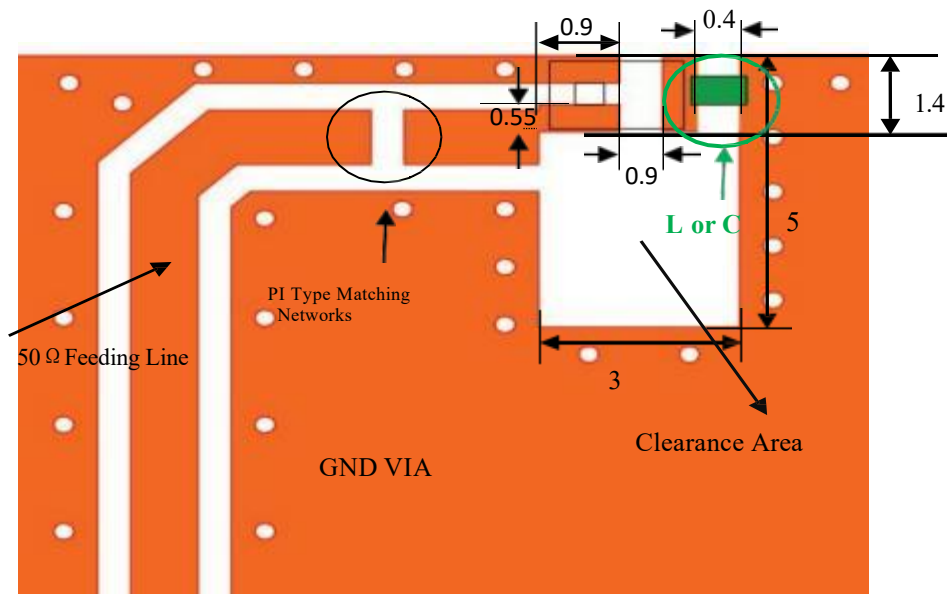
(Side View)

Symbols	L	W	T	A
Dimensions	2.0 ± 0.2	1.25 ± 0.2	0.6 ± 0.1	0.6 ± 0.1

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Evaluation Board and Matching Circuits



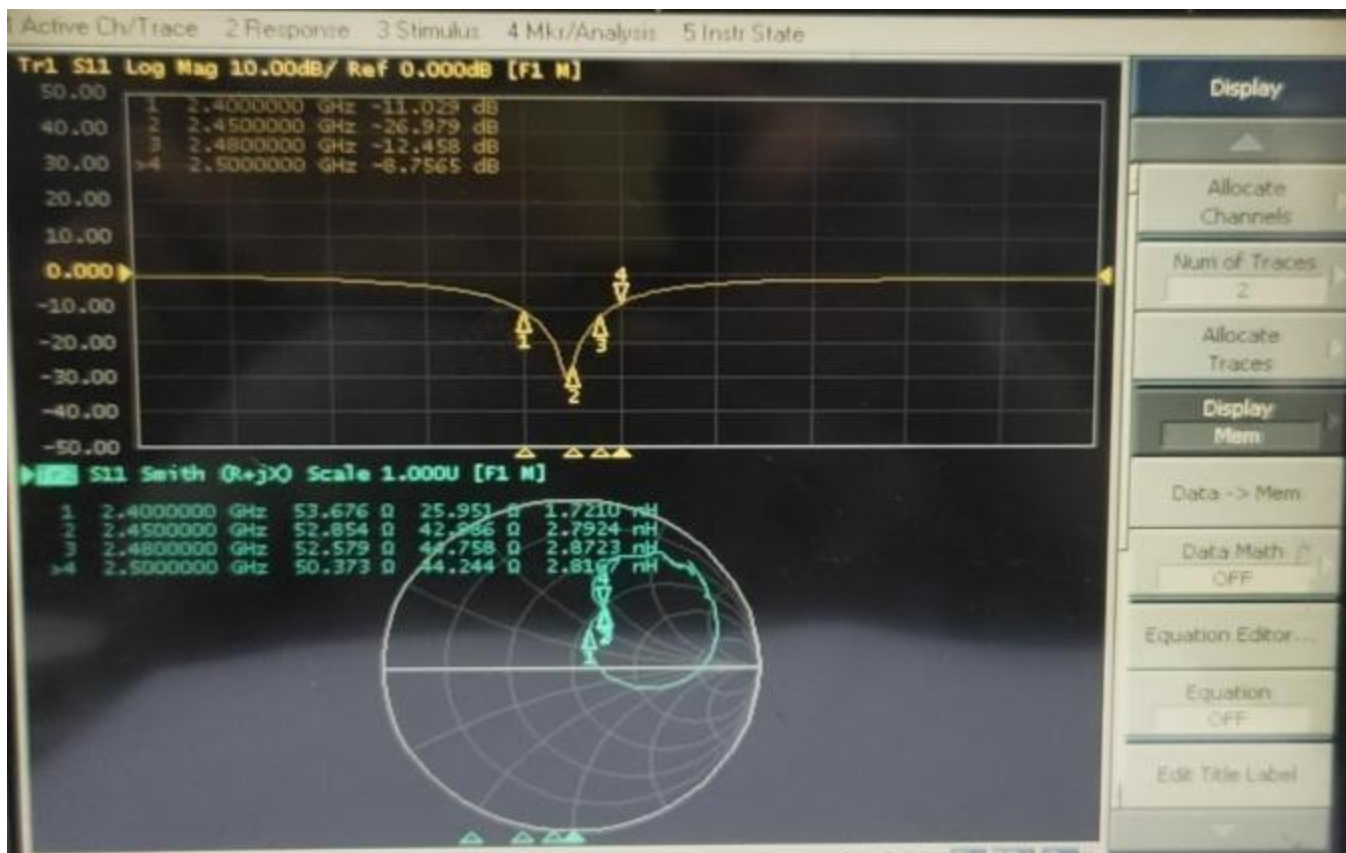
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Electrical Characteristics

No.	Item	Specifications
1	Central Frequency	2450MHz
2	BandWidth	100MHz typ.
3	Peak Gain	2.7 dBi
4	Return Loss	≤ 2.0
5	Polarization	Linear
6	Azimuth Beam width	Omni-directional
7	Impedance	50 Ω

Characteristic curve

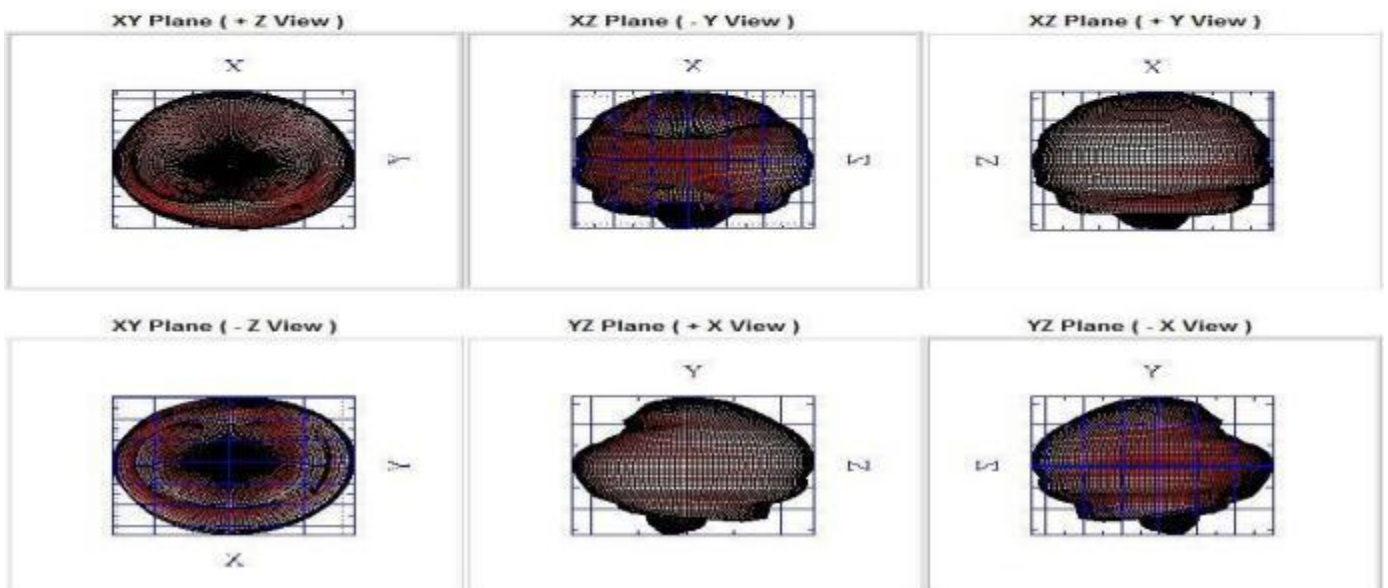
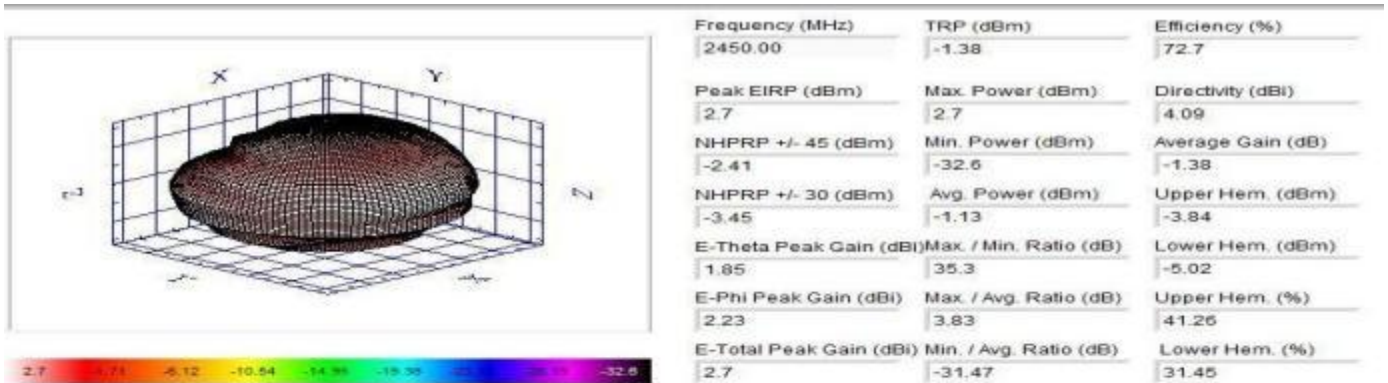
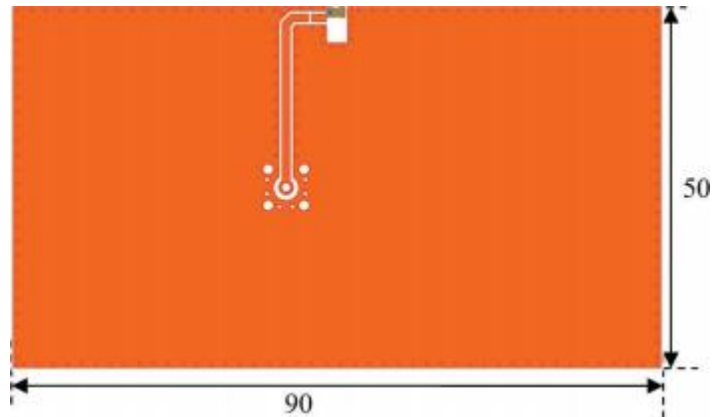
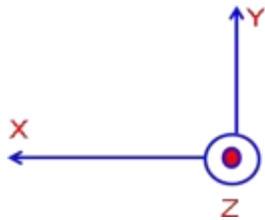


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Radiation Pattern

coordinates:



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Post Dependability Tolerance

Dependability Test

Temperature range	25±5℃
Relative Humidity range	55~75%RH
Operating Temperature range	-40℃~+85℃
Storage Temperature range	-40℃~+85℃

Item	Post Dependability Tolerance
Central Frequency	±5 MHz
Band Width	±5 MHz
Gain	±0.1 dBi
V.S.W.R (in BW)	±0.1

Vibration Resist

The device should satisfy the electrical characteristics specified in paragraph 8.1~8.4 after applied to the vibration of 10 to 55Hz with amplitude of 1.5mm for 2 hours each in X , Y and Z directions.

Drop Shock

The device should satisfy the electrical characteristics specified in paragraph 8.1~8.4 after dropping onto the hard wooden board from the height of 100cm for 3 times each facet of the 3 dimensions of the device.

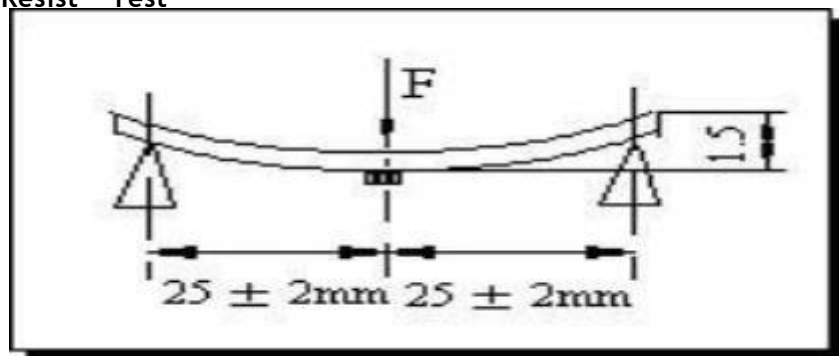
Solder Heat Proof

The device should be satisfied after preheating at 120℃~150℃ for 120 seconds and dipping in soldering Sn at 255℃+10℃ for 5±0.5 seconds , or electric iron 300℃-10℃ for 3±0.5 seconds , without damage.

Adhesive Strength of Termination

The device have no remarkable damage or removal of the termination after horizontal force of 5N(≤0603); 10N(>0603)with 10±1 seconds.

Bending Resist Test



Weld the product to the center part of the PCB with the thickness

1.6±0.2mm as the illustration shows, and keep exerting force arrow-ward on it at speed of :1mm/S , and hold for 5±1S at the position of 1.5mm bending distance , so far , any peeling off of the product metal coating should not be detected .

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Moisture Proof

The device should satisfy the electrical characteristics specified in paragraph 8.1~8.4 after exposed to the temperature $60\pm 2^{\circ}\text{C}$ and the relative humidity 90~95% RH for 96 hours and 1~2 hours recovery time under normal condition.

High Temperature Endurance

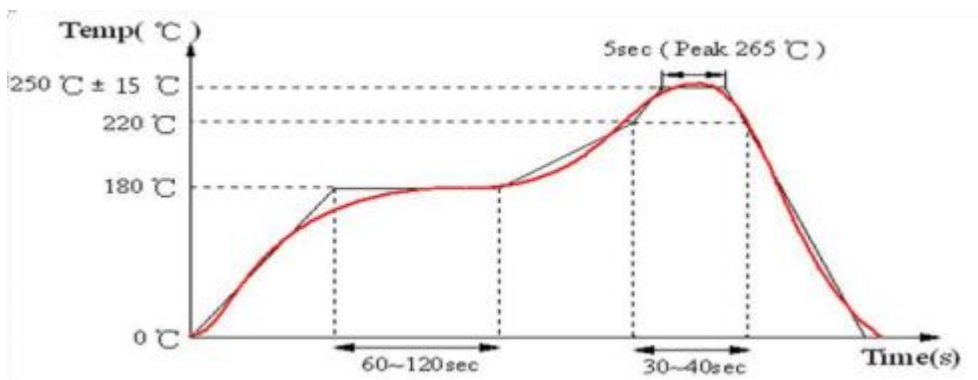
The device should satisfy the electrical characteristics specified in paragraph 8.1~8.4 after exposed to temperature $85\pm 5^{\circ}\text{C}$ for 96 ± 2 hours and 1~2 hours recovery time under normal temperature.

Low Temperature Endurance

The device should also satisfy the electrical characteristics specified in paragraph 8.1~8.4 after exposed to the temperature $-40^{\circ}\text{C}\pm 5^{\circ}\text{C}$ for 96 ± 2 hours and to 2 hours recovery time under normal temperature.

Temperature Cycle Test

The device should also satisfy the electrical characteristics specified in paragraph 8.1~8.4 after exposed to the low temperature -40°C and high temperature $+85^{\circ}\text{C}$ for 30 ± 2 min each by 5 cycles and 1 to 2 hours recovery time under normal temperature.

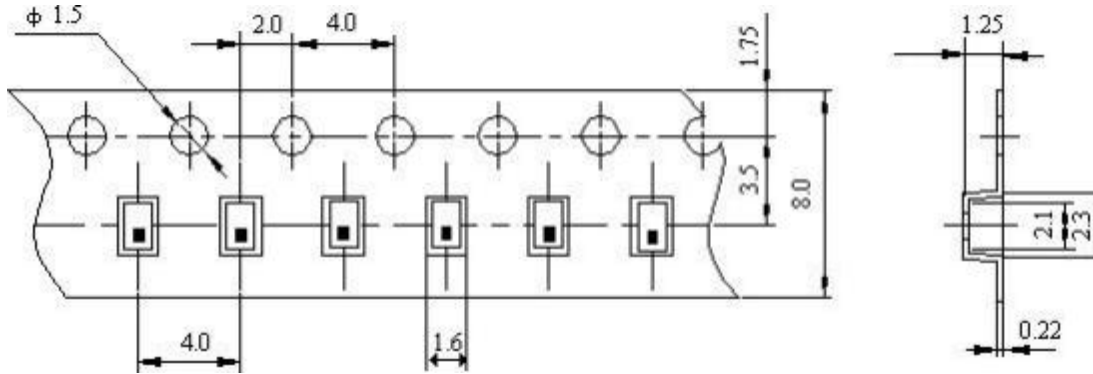
Reflow Soldering Standard Condition

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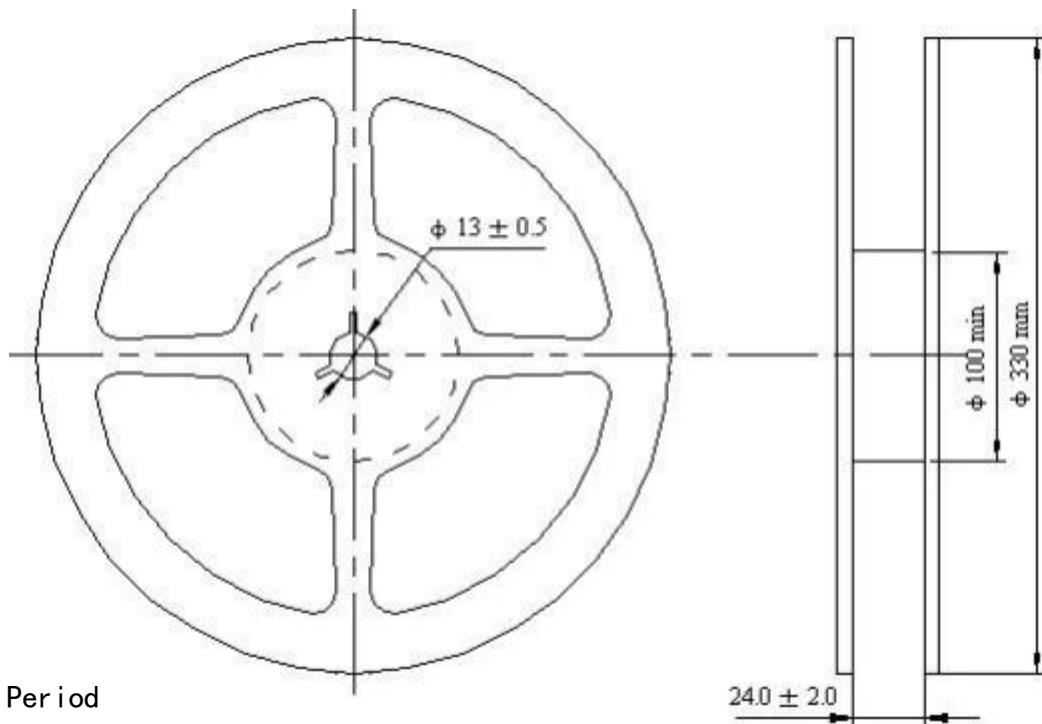
Packaging and Dimensions (2012)

Plastic Tape



Remarks for Package

Reserve a length of 150~200mm for the trailer of the carrier and 250~300 mm for the leader of the carrier and further 250mm of cover tape at the leading part of the carrier.
Reel (4000 pcs/Reel)



Storage Period

Product should be used within twelve months of receipt.

MSL 1 / Storage Temperature Range : -40~85 degree C, Humidity : <60%RH

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